Charles .	ES	CC
400	(0)	

Component Title:

DIODES, MICROWAVE, SILICON, MULTIPLIER AND PIN, BASED ON TYPES DH 2XX AND DH 50XXX

Page 1

	<u> </u>		ON TYPES DH 2	(X AND DH 50)	(XX	ER AND PIN, BA	Appl	. No.
2000		Executive Member:	CNES		Date:	01/10/2014	22	5 F
Components (including	ng series and families) s	submitted for Extension	n of Qualification	Approval:				
ESCC COMPONENT NO.	VARIANTS	RANGE OF CO	MPONENTS	BASEI ON	22	TEST VEHICLE / S	COMPONI	
5512/016	10-56	56 CT = 0.4 to 7.2 pF DH267 to I			H294   5512	2/016-11	All other variant	s
Component Ma COBHAM MICROWA		Location of Ma 31, avenue de la Ba 91978 Villebon Sur France	anufacturing Plan Itique Yvette	t(s) 3	Date of originate:  Certificate R	inal qualification a 01/06/1995 def No. 225	approval:	4
ESCC Specifications Maintenance of qualifications 5010  Detail(s): 5512-016	cation testing: Issue: 1	Deviations to LVT te used: No ⊠ Yes Deviation from curre No ⊠ Yes	(supply of	letails in Box	reference an	Extension Reported date:		7
Summary of procurem	ent or equivalent test re	sults during current va	alidity period in su	pport of this an	plication (those	e to ESCC listed t	licet\	8
Project Name	Testing Level	LAT		Date code	phoduon (those		/ Delivered	
Various		LAT2	Various	17 17.	440	W.75 / V.7		
PID changes since sta	rt of qualification	9	Current PID V	erified by:	10.00	J.L. Roux	ntative	10
Minor* ⊠ Major* □ * <sub> </sub>	Provide details in box:		Issue: D	50 9/09/2014	\$15000 H 5000 D 5000 D	Date:	27/09/2014	
Current Manufacturing	facilities surveyed by:	(Name	ESA and CNE		on		to enter a date	11
Satisfactory: Report Reference:	Yes ⊠ See Box 14	No   Expl	lain					



Component title:

DIODES, MICROWAVE, SILICON, MULTIPLIER AND PIN, BASED

ON TYPES DH 2XX AND DH 50XXX

Executive Member:

CNES

Date: 01/10/2014

Page 2
Appl. No.

12

Failure Analysis, DPA, NCCS available:

Yes

No

(Supply data)

Ref. No's and purposes:

12

14

The undersigned hereby certifies on behalf of the ESCC Executive - that the above information is correct; - that the appropriate documentation has been evaluated; - that full compliance to all ESCC requirements is evidence (except as stated in box 15;) - that the reports and data are available at the ESCC Executive and therefore applies on behalf of CNES as the responsible Executive Member for ESCC qualification status to be extended to the component(s) listed herein.

Date:

10/10/2014

P.I. Philippe LAY (Head of Components and Qualification Section) for JP.BUSSENOT

(Signature of the Executive Coordinator)

Continuation of Boxes above

Box 9: Editorial Changes (merge of PIDs on DH2XX and DH5xx), back end moved to ground floor.

Box 11: Audit report QCS/LB/08010 (28.01.2008) and Audit Close-out report QCS/LB/090302 (31.03.2009). Additional survey conducted on 08.03.2010 in the frame of a NRB on DH76xxx diodes.

ESCC AVOIT (CWE) AND EJA) OF COBHAM AT THE SAME ADDRESS TOOK PLACE IN SEPTEMBER 2014 IN RECATION TO THE OVACIFICATION OF ISOLATORS AND CIRCULATORS (THE DMS IS THE SAME AND THE BACK. END AND TEST AREA) ARE ALSO COMMON).

NEF: ESA-TECRES-RP-0508



Component title:

DIODES, MICROWAVE, SILICON, MULTIPLIER AND PIN, BASED ON TYPES DH 2XX AND DH  $50\mathrm{XXX}$ 

Page 3

Appl. No.

Executive Member: CNES

Date: 01/10/2014

225 F

			2231
Non compliance	to ESCC requirements:		L
No.:	Specification	Paragraph	Non compliance
Additional tasks rinoncompliance:		nce for ESCC qualification or rationale for accep	
Executive Manage Application Approv	val: Yes □ No		
Date:			Signature, ESA Representative



DIODES, MICROWAVE, SILICON, MULTIPLIER AND PIN, BASED ON TYPES DH 2XX AND DH  $50\mathrm{XXX}$ 

Date: 01/10/2014

Page 4 Appl. No.

225 F

18

## ANNEX 1: LIST OF TESTS DONE TO SUPPORT EXTENSION OF QUALIFICATION

Tests conducted in compliance with:

ESCC 5010 generic specification; Chart V (for ESCC/QPL parts);
Or PID-TFD (for ESCC/QML parts)

Or PID-TFD

Tests vehicle identification/description:

DH267-511 (5512016-11)	

Component Title:

Executive Member:

Detail Specification reference:

5 T

Chart V	Test	Tick when done	Conditions	Date Code Diffusion Lot	Tested Qty	No. of Rejects	Comments if not performed. Comments on Rejection
	Thermal Shock Test	×	ESCC 5010 Para. 9.5.2	DC1351- 13J011A	6	0	
	Shock Test		MIL-STD-750 Test Method 2016				Not applicable (agreed deviation)
groups	Vibration Test		MIL-STD-750 Test Method 2056				Not applicable (agreed deviation)
al Sub	Constant Acceleration		MIL-STD-750 Test Method 2006				Not applicable (agreed deviation)
hanic	Seal Test		MIL-STD-750 Test Method 1071	DC1351- 13J011A	6	0	
al/Mec	Moisture Resistance	×	MIL-STD-750 Test Method 1021	DC1418- 05P004	6	0	Done on a different type with the same package (M208)
nment	Seal Test	×	MIL-STD-750 Test Method 1071	DC1351- 13J011A	6	0	
Environmental/Mechanical Subgroups	Electrical Measurements at Room Temp.		Table 2 of the Detail Specification	DC1351- 13J011A	6	0	
	External Visual Inspection	×	ESCC Basic Specification No. 20500	DC1351- 13J011A	6	0	
	Operating Life	×	MIL-STD-750 Test Method 1026	DC1351- 13J011A	8	0	
Endurance Subgroup	Electrical Measurements during Endur. Test	×	Table 6 of the Detail Specification	DC1351- 13J011A	8	0	
El Si	External Visual Inspection	×	ESCC Basic Specification No. 20500	DC1351- 13J011A	8	0	





Component title:

DIODES, MICROWAVE, SILICON, MULTIPLIER AND PIN, BASED

ON TYPES DH 2XX AND DH 50XXX

Executive Member: CNE

CNES

Date: 01/10/2014

Page 5

Appl. No.

Chart V	Test	Tick when done	Conditions	Date Code Diffusion Lot	Tested Qty	No. of Rejects	Comments if not performed. Comments on Rejection
p –	Electrical Measurements at Room Temp.		Table 2 of the Detail Specification	DC1351- 13J011A	4	0	
Subgrou	Electrical Measurements at High & Low Temp's	×	Table 3 of the Detail Specification	DC1351- 13J011A	4	0	
Electrical Subgroup – Electrical Measurements	External Visual Inspection	$\boxtimes$	ESCC Basic Specification No. 20500	DC1351- 13J011A	4	0	
	Special Testing		The Detail Specification				Not applicable (agreed deviation)
group y ests	Solderability Test	×	MIL-STD-750 Test Method 2026	DC1351- 13J011A	2	0	
Electrical Subgroup  - Assembly Capability Tests	Permanence of Marking		ESCC Basic Specification No. 24800	DC1351- 13J011A	2	0	
Electr	Terminal Strength		MIL-STD-750 Test Method 2036				Not applicable for M208b package
lal							
Additional							
A.							

(\*) DENATIONS AGREEN IN EJC(5512/016, Para. 4.2.5

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Box 22

Additional Comments.

## APPLICATION FOR EXTENSION OF ESCC QUALIFICATION APPROVAL

DIODES, MICROWAVE, SILICON, MULTIPLIER AND PIN, BASED ON TYPES DH 2XX AND DH  $50\mathrm{XXX}$ 

Executive Member: CNES Date: 01/10/2014 Page 7

Appl. No. 225 F

Component title:

	No	OTES ON THE COMPLETION OF THE APPLICATION FORM FOR ESCC QUALIFICATION EXTENSION APPROVAL
1	ENTRIES	
	Form heading	shall indicate: - the title of the component as given in its detail specification or the name of the series, family, - the Executive Member; - the entering date; - the certificate number and its sequential suffix.
	Box 1	shall provide details given in the table; in particular there shall be listed: - the variants or range of variants; - the range of components (the ESCC code is recommended to indicate the values or values range, the tolerance, the voltage, etc); the designation given in the detail specification as 'base on'; - under Test Vehicle enter either an ESCC code or the specific characteristic capable of identifying the component tested (e.g., voltage of coil for a relay); - under component similar enter a cross if relevant.
	Box 2; 3 and 4	As per QPL entry; otherwise, an explanation of the changes must be supplied.
	Box 5	Will show the ESCC Generic and Detail specifications, including issue number and revision letter, current at the time the tests reported were performed. If the specifications are different from those current on the date of the application, see Box 6.
	Box 6	Will show the deviations from the Generic and Detail Specifications listed in Box 5, in particular deviations from testing. In case of deviations this must be listed in Box 15. In case the referenced specification in Box 5 have currently a different issue and/or revision indicate also whether the test data deviates or not from such current documents.
	Box 7	Must reference the report(s) supplied in support of the application.
	Box 8	Should provide the details of procurement to the full ESCC System, documentation of all of which should already have been delivered to the ESCC Executive under the terms of the relevant Generic Specification. An appropriate table has been drawn in this box.
	Box 9	If the PID evolved after the Original Qualification or after the last Extension of Qualification, adequate details of such evolution shall be provided together with the reasons for the changes. Major changes shall be clearly marked.
	Box 10	Identify the current PID issue status, date and actual date of verification. The date of verification of the current PID should be arranged as close as possible to the required date of extension.
	Box 11	This box can be completed only after a physical visit to the plant to confirm that no unexplained changes occurred and that the practices, procedures, material, etc. used in manufacturing the components are as described in the PID. This survey shall be carried out in accordance with the requirements of ESCC Basic Specification No. 20200 and its findings shall be recorded.
	Box 12	Provide details of, or reference to, any Destructive Physical Analysis (DPA) and Failure Analysis reports as well as any Nonconformance(s) (NCCS) occurred during the qualification validity period, stating if established corrective action have produced satisfactory results.
	Box 13	Enter only the name of the Executive Member (i.e., CNES, DLR, ESTEC, etc.) and the signature of the responsible Executive Coordinator.
	Box 14	To be used when there is a need to expand any of the boxes from 1 through 12. Identify box affected and reference the Box 14 in the relevant Box. Box 14 can be broken into 14a, 14b, etc. if several boxes have to be expanded.
E	3ox 15	Fill in Table as requested.
E	3ox 16	Any additional action deemed necessary by the Executive Member to bring the submitted data to a standard likely to be accepted by the ESCC Executive should be listed herein or the reason(s) to accept the noncompliance.
E	3ox 17	All Executive Manager recommendations on the application itself, special conditions or restrictions, modifications of the QPL or QML entry, letters to the manufacturer, etc. shall be entered clearly in Box 19, signed by the representative for ESA, and dated.
E	Box 18	Fill in Table as requested.
E	Box 19	Confidential Details of PID changes including those of a confidential nature, shall be provided.
E	3ox 20	State noncompliance with reference to specification(s) and paragraph(s). To simplify reference in Box 16 each nonconformance shall be sequentially numbered. If relevant state 'None'.
E	3ox 21	Any additional action deemed necessary by the Executive Member to bring the submitted data to a standard likely to be accepted by the ESCC Executive should be listed herein or the reason(s) to accept the noncompliance.
_		